



UPDATE CHANGE NOTIFICATIONGeneric Copy

11 Feb 2008**SUBJECT: ON Semiconductor Update Notification # UN16099****TITLE: Update Notification to Product Bulletin 16059 announcing Package Pin Removal for NCP1396****PROPOSED FIRST SHIP DATE: 11 Feb 2008****AFFECTED PRODUCT DIVISION(S): Analog IC****FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Scott Brow <Scott.Brow@onsemi.com>**NOTIFICATION TYPE:**

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This serves as an Update Notification to customers who received Product Bulletin PB16059 which announced a package pin removal for the NCP1396..

Due to supply issues on the lead frame change described in PB 16059, ON Semiconductor was unable to convert the line and meet the proposed first ship date of October 23, 2007 as listed. At this time, the line is now ready to convert; and all product shipped marked with a date code of 806 (WW06 2008) or newer, will be produced with the updated lead frame.

For assistance, please contact;

Product Engineer: Scott Brow
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Email: Scott.Brow@onsemi.com

Product Marketing: Christophe Warin
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Update Notification #16099

AFFECTED DEVICE LIST

PART

NCP1396ADR2G
NCP1396BDR2G